

Amendments to the Claims:

1. **(Currently Amended)** A semiconductor device comprising:
a semiconductor element that has a first surface on which an external connection terminal is formed and a second surface that faces the first surface, and a thickness of $10\mu\text{m}$ or more and $150\mu\text{m}$ or less;

a plate that faces the second surface; and
a resin binder that adheres the second surface and the plate,
wherein the plate has ~~the~~ a rigidity higher than that of the semiconductor element;
an outer shape of the plate is larger than that of the semiconductor element; and
the resin binder covers a side face of the semiconductor element, and furthermore at a portion that is interposed between the second surface and the plate the resin binder allows the semiconductor element to deform in a thickness direction thereof.

2. **(Currently amended)** The semiconductor device according to claim 1, wherein the resin binder covers at least an edge ~~that is formed of defined by~~ a side face and the second surface of the semiconductor element, about the outer periphery of the semiconductor element.

3. **(Previously presented)** The semiconductor device according to claim 1, wherein the resin binder covers the side face over an entire circumference of the semiconductor element.

4. **(Previously presented)** The semiconductor device according to claim 1, wherein the resin binder covers only a corner of the side face of the semiconductor element.

5. **(Canceled)**

6. **(Original)** The semiconductor device according to claim 1, wherein the external connection terminal is provided with a bump.

Claims 7 and 8. **(Cancelled)**

9. **(Previously presented)** The semiconductor device according to claim 1, wherein the semiconductor element includes a re-wiring layer on the first surface, the re-wiring layer has a surface electrode formed on a surface and an internal electrode formed inside thereof, and the internal electrode connects the surface electrode and the external connection terminal.

10. **(Original)** The semiconductor device according to claim 9, wherein the surface electrode is provided with a bump.

11. **(Currently Amended)** A semiconductor device assembling method in which a semiconductor element and a plate that is higher in the rigidity than the semiconductor element are adhered ~~with~~ via a resin binder, the semiconductor element having a first surface on which an external connection terminal is formed and a second surface ~~that faces opposite~~ opposite the first surface, the second surface being adhered to the plate, said method comprising:

~~a first step of~~ roughly processing ~~according to mechanical~~ by mechanically polishing a side opposite to the first surface on which an external connection terminal of the semiconductor element is formed, followed by further applying finishing to obtain a second surface from which a damaged layer is removed and to make a thickness of the semiconductor element 10 μ m or more and 150 μ m or less;

~~a second step of~~ supplying the resin binder to a plate member including the plate;

~~a third step of~~ adhering the second surface and the plate in an aligned state by use of the resin binder; and

~~fourth step of~~ cutting the plate from the plate member.

12. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein, ~~in the third step said adhering~~, the resin binder is formed ~~with to cover~~ an outer periphery of the semiconductor element ~~covered~~.

13. **(Currently amended)** The semiconductor device assembling method according to claim 12, wherein ~~by use of a decrease in the viscosity of the resin binder owing to heating~~, in said adhering, the resin binder is spread to a side face of the semiconductor element to cover the outer periphery by decreasing the viscosity of the resin binder by heating

14. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein ~~the second step is a step of said supplying comprises~~ supplying a ~~the~~ resin binder by an amount necessary to cover a side face of the semiconductor element.

15. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein, ~~in the second step said supplying~~, the resin binder supplied is liquid resin, the plate member has a projection surrounding the plate, and the liquid resin is supplied inside of the projection.

16. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein, in said supplying, the resin binder is ~~in~~ supplied as a resin binder sheet, and ~~the second step is a step of adhering the resin binder sheet~~ is adhered to the plate member.

17. **(Currently Amended)** The semiconductor device assembling method according to claim 11, wherein
~~the plate member has~~ said plate constitutes one of a plurality of the plates;
said semiconductor element constitutes one of a plurality of semiconductor elements; and

~~the third step~~ said adhering includes ~~a step of~~ mounting the semiconductor element ~~through elements via~~ the resin binder for each of the plates ~~that of~~ the plate member ~~has~~, and ~~a step of~~ heating the plate member on which the semiconductor elements are mounted.

18. **(Currently Amended)** The semiconductor device assembling method according to claim 17, wherein ~~the third step simultaneously carries out the step of~~, in said adhering, said mounting and the step of said heating are carried out simultaneously.

19. **(Currently Amended)** The semiconductor device assembling method according to claim 18, wherein ~~the third step~~ said adhering is carried out by use of a semiconductor element mounting means of the semiconductor element that are provided with device that includes a heating means device.

20. **(Original)** The semiconductor device assembling method according to claim 11, wherein the semiconductor element has a re-wiring layer on the first surface.